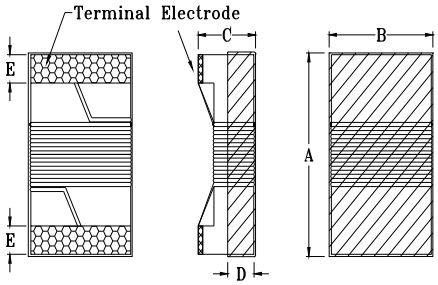
High Frequency Winding Type Chip Inductor SWI0805O-SERIES

1. Features

1. Ceramic core wire wound construction.
2. No batch to batch variations in inductance.
3. High Reliability due to ceramic wire wound construction.
4. High frequency application.
5. Small footprint as well as low profile.
6. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
7. Operating temperature -40~+125℃(Including self - temperature rise).

2. Dimensions



Size	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
SWI0805	2.40 max.	1.60 max.	1.40 max.	0.51 ref.	0.44±0.10

Unit:mm

3. Part Numbering

SWI	0805	O	-	2N0	S
A	B	C		D	E

A: Series
B: Dimension LxW
C: Category Code Industrial Grade
D: Inductance 2N0=2.0nH
E: Inductance Tolerance C=±0.2nH , S=±0.3nH, J=±5% ,K=±10%

4. Specification

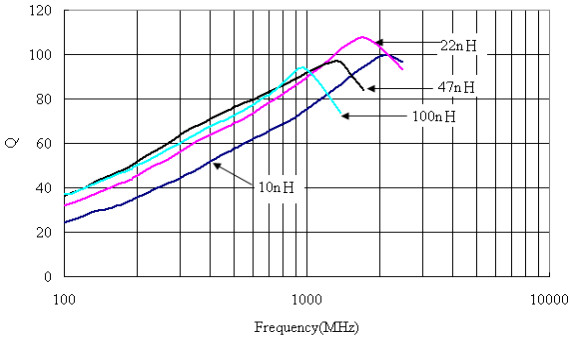
Part Number	Inductance (nH)	Tolerance	Test Frequency (Hz)	Q min.	Test Frequency (MHz)	Rated Current (mA) max.	DCR (Ω) max.	SRF (MHz) min.
SWI0805O-2N0□	2.0	C,S	0.1V/250M	70	1500	800	0.03	8000
SWI0805O-3N9□	3.9	C,S	0.1V/250M	70	1500	800	0.04	5750
SWI0805O-4N7□	4.7	C,S	0.1V/250M	70	1500	800	0.04	5750
SWI0805O-6N8□	6.8	C,J,K	0.1V/250M	70	1500	800	0.06	5500
SWI0805O-7N5□	7.5	C,J,K	0.1V/250M	70	1000	800	0.06	4500
SWI0805O-8N2□	8.2	C,J,K	0.1V/250M	70	1000	800	0.06	4700
SWI0805O-10N□	10	J,K	0.1V/250M	70	1000	600	0.08	4200
SWI0805O-12N□	12	J,K	0.1V/250M	80	1000	600	0.08	4000
SWI0805O-15N□	15	J,K	0.1V/250M	80	1000	600	0.10	3400

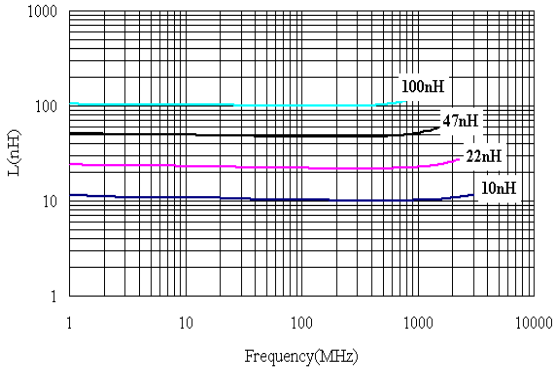
Part Number	Inductance (nH)	Tolerance	Test Frequency (Hz)	Q min.	Test Frequency (MHz)	Rated Current (mA) max.	DCR (Ω) max.	SRF (MHz) min.
SWI0805O-18N□	18	J,K	0.1V/250M	80	1000	600	0.10	3300
SWI0805O-22N□	22	J,K	0.1V/250M	60	500	600	0.12	2600
SWI0805O-24N□	24	J,K	0.1V/250M	60	500	600	0.12	2000
SWI0805O-27N□	27	J,K	0.1V/250M	60	500	600	0.12	2500
SWI0805O-33N□	33	J,K	0.1V/250M	60	500	600	0.13	2050
SWI0805O-36N□	36	J,K	0.1V/250M	65	500	600	0.13	1700
SWI0805O-39N□	39	J,K	0.1V/250M	65	500	600	0.15	2000
SWI0805O-43N□	43	J,K	0.1V/200M	65	500	600	0.15	1650
SWI0805O-47N□	47	J,K	0.1V/200M	65	500	600	0.17	1650
SWI0805O-56N□	56	J,K	0.1V/200M	65	500	600	0.19	1550
SWI0805O-68N□	68	J,K	0.1V/200M	60	500	500	0.22	1450
SWI0805O-82N□	82	J,K	0.1V/150M	55	500	400	0.40	1300
SWI0805O-R10□	100	J,K	0.1V/150M	55	500	400	0.52	1200
SWI0805O-R11□	110	J,K	0.1V/150M	55	500	400	0.52	1200
SWI0805O-R12□	120	J,K	0.1V/150M	50	250	400	0.55	1100
SWI0805O-R15□	150	J,K	0.1V/150M	50	250	400	0.73	920
SWI0805O-R18□	180	J,K	0.1V/100M	50	250	400	0.88	870
SWI0805O-R22□	220	J,K	0.1V/100M	50	250	340	1.18	850
SWI0805O-R24□	240	J,K	0.1V/100M	48	250	330	1.20	690
SWI0805O-R27□	270	J,K	0.1V/100M	48	250	310	1.36	650
SWI0805O-R33□	330	J,K	0.1V/100M	40	250	300	1.40	600
SWI0805O-R39□	390	J,K	0.1V/100M	25	250	290	1.50	560
SWI0805O-R47□	470	J,K	0.1V/50M	25	100	250	1.76	375
SWI0805O-R56□	560	J,K	0.1V/25M	23	100	210	1.90	340
SWI0805O-R62□	620	J,K	0.1V/25M	23	100	205	2.00	220
SWI0805O-R68□	680	J,K	0.1V/25M	23	100	200	2.15	200
SWI0805O-R75□	750	J,K	0.1V/25M	20	100	185	2.25	200
SWI0805O-R82□	820	J,K	0.1V/25M	20	100	170	2.50	200
SWI0805O-1R0□	1000	J,K	0.1V/25M	15	50	170	2.60	100

Note:

- All test data referenced to 25℃ ambient.
- DC current at 25°C that causes the specified inductance drop from its value without current.
- Current that causes the specified temperature rise from 25°C ambient.

This information is for reference only and does not represent absolute maximum ratings.





5. Recommended PC Board Pattern

Chip size							Land Patterns For Reflow Soldering		
Series	Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	L(mm)	G(mm)	H(mm)
SWI	0805	2.40max	1.60max	1.40max	0.51 ref	0.44±0.10	2.80	1.29	1.78

